

Appl. No. : 09/471,071
Filed : December 21, 1999

REMARKS

The Applicant thanks the Examiner for his careful and thoughtful examination of the present application. Claims 8-23 and 25-30 are pending in the present application

Rejection Of Claims 8, 9, 11-18, 21-23 and 25-28 Under 35 U.S.C. § 102

The Office Action rejected Claims 8, 9, 11-18, 21-23 and 25-28 under 35 U.S.C. § 102 as being anticipated by U.S. Patent No. 6,309,915, issued to Distefano (the Distefano patent). Applicant respectfully traverses this rejection and the Examiner's characterization of the cited reference.

The Examiner asserts that Distefano teaches a die 2, a die attach layer or compliant material 11 over the die, and an array of solder balls 12 over the die attach layer 11. Applicant believes that the Examiner is referring to solder balls 12 and 13 as shown in Figures 6 and 7 of Distefano. However, neither of these figures discloses or suggests that the solder balls are provided over a die attach layer, as recited by Claim 8 and 15, that an adhesive layer having the claimed properties is provided between a chip and an array of solder balls, as recited by Claims 17 and 21, or that conductive terminals are provided over a compliant material with certain claimed properties, as recited by Claim 25 as amended. Rather, Distefano in Figure 6 shows the solder balls 12 and 13 spaced away from the compliant layer 11. With respect to Figure 7, compliant spacers 11a are depicted, though no compliant layer is disclosed.

Accordingly, Applicant respectfully submits that Claims 8, 15, 17, 21 and 25 are in condition for allowance, and such action is respectfully requested. Claims 9, 11-14, 16, 18-20, 22-23 and 26-30, which depend from the independent claims discussed above, are believed to be patentable for the same reasons articulated above, and because of the additional features recited therein.

Rejection Of Claim 10 Under 35 U.S.C. § 103

The Office Action rejected Claim 10 under 35 U.S.C. § 103 as being unpatentable over the Distefano patent in view of U.S. Patent No. 6,265,782, issued to Yamamoto (the Yamamoto patent). The Applicant respectfully traverses this rejection because the Distefano patent, alone or in combination with the Yamamoto patent, fails to teach or suggest the elements of the independent claims discussed at length above. See M.P.E.P. § 2143 (stating that in order to

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establish a *prima facie* case of obviousness for a claim, the prior art references must teach or suggest all the claim limitations). Claim 10, which depends from Claim 8, is believed to be patentable for the same reasons articulated above with respect to Claim 8, and because of the additional features recited therein.

Conclusion

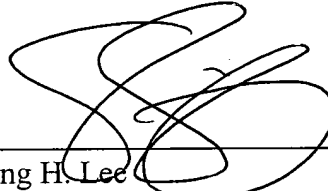
The Applicant has endeavored to address all of the Examiner's concerns as expressed in the outstanding Office Action. In view of the above remarks, the Applicant submits that the application is in condition for allowance and respectfully requests the same. If the Examiner finds any remaining impediment to the prompt allowance of these claims that could be clarified with a telephone conference, the Examiner is invited to initiate the same with the undersigned.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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Dated: 6'15'05

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